

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	476231	(anneal\$3 heat\$3 bak\$3) same (HCl or hydrochloric or hydrofluoric or hydrobromic or hydroiodic or HBr or HF or HI or chlorine or fluorine or bromine or iodine or halogen or "Cl.sub.2" "Br.sub.2" "F.sub.2" "I.sub.2" or cl br f i)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:30
2	L8	162793	(treat\$4 pretreat\$ condition\$3 precondition\$3 prepar\$3 smooth\$3 roughness) same 1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:23
3	L15	11414	8 same (silicon or semiconductor or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:25
4	L22	263688	(anneal\$3 heat\$3 bak\$3) with (HCl or hydrochloric or hydrofluoric or hydrobromic or hydroiodic or HBr or HF or HI or chlorine or fluorine or bromine or iodine or halogen or "Cl.sub.2" "Br.sub.2" "F.sub.2" "I.sub.2" or cl br f i)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:24
5	L29	73880	22 same (treat\$4 pretreat\$ condition\$3 precondition\$3 prepar\$3 smooth\$3 roughness)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:52
6	L36	49120	epitax\$5 near25 (si silicon semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:25
7	L43	5176	29 same (silicon or semiconductor or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:08
8	L57	432	36 and 43	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:53
9	L64	370	57 and @ad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:54
10	L71	122	57 and @rlad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:54
11	L78	381	64 71	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:28
12	L85	172356	(anneal\$3 heat\$3 bak\$3) same (HCl or hydrochloric or hydrofluoric or hydrobromic or hydroiodic or HBr or HF or HI or chlorine or fluorine or bromine or iodine or halogen or "Cl.sub.2" "Br.sub.2" "F.sub.2" "I.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:03
13	L92	80697	(anneal\$3 heat\$3 bak\$3) with (HCl or hydrochloric or hydrofluoric or hydrobromic or hydroiodic or HBr or HF or HI or chlorine or fluorine or bromine or iodine or halogen or "Cl.sub.2" "Br.sub.2" "F.sub.2" "I.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:32
14	L99	25079	92 same (treat\$4 pretreat\$ condition\$3 precondition\$3 prepar\$3 smooth\$3 roughness)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:53
15	L106	363	36 and 99	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:53
16	L113	313	106 and @ad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:54
17	L120	110	106 and @rlad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:08
18	L127	321	113 120	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 11:54
19	L134	168693	(anneal\$3 heat\$3 bak\$3) same (HCl or hydrochloric or hydrofluoric or hydrobromic or hydroiodic or HBr or HF or HI or chlorine or fluorine or bromine or iodine or (halogen not adj lamp) or "Cl.sub.2" "Br.sub.2" "F.sub.2" "I.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:05
20	L141	27524	134 same ("H.sub.2" or hydrogen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:06
21	L148	2860	141 same (silicon or semiconductor or si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:08
22	L155	721	148 and @rlad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:08

	L #	Hits	Search Text	DBs	Time Stamp
23	L162	2510	148 and @ad<19990421	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:09
24	L169	2593	155 162	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 12:09
25	L176	531	36 and 169	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:33
26	L183	285	(Goesele or bruel).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:33
27	L190	10	183 and 36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:38
28	L197	15949	(cleav\$3 split\$4 detach\$4 separat\$4) and 36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:40
29	L204	489	(cleav\$3 split\$4 detach\$4) same 36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:40
30	L211	187	(cleav\$3 split\$4 detach\$4) near20 36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/06 14:41